

NEU: IXYS PFC-Module für Leistungsanwendungen

1~ und 3~ Versionen

1~ PFC MODULES (1~ BRIDGE + MOSFET BOOST)

Features:

- V_{ds}: 500V, I_d:35A and 47A, Low R_{ds(on)} HDMOS™ process
- 1~ diode input bridge feeding a MOSFET/FRED boost circuit
- Package with DCB ceramic base plate with Isolation Voltage 3600 V~
- Soldering connections for PCB mounting, Low package inductance for high speed switching, Kelvin source for easy drive

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PartNumber	VDSS max (V)	ID25 Tc=25°C (A)	RDS(on) max Tj=25°C (mOhm)	VRRM BoostDiodes (V)	VRRM RectifierDiodes (V)	Ckt Diag	Package Style	Status
VUM24-05N	500	35	0.12	600	800	VUM...	V1-B-Pack	Active Part
VUM33-05N	500	47	0.12	600	800	VUM...	V1-B-Pack	Active Part
VUM33-06PH	600	47	0.12	600	800	VUM...	V1-B-Pack	Active/New Product

3~ PFC MODULES

Features:

- 1~ diode input bridge feeding a MOSFET/FRED or an IGBT/FRED boost circuit to form one unit of 3~ PFC front
- V_{ds}: 500V, I_d: 35A rated MOSFET in a Diode Bridge rated at V_{rrm}: 600V, I_{dav}: 40A in VUM25-05E for upto 10KW power
- V_{ces}: 1200V, I_c: 95A , RBSOA rated NPT IGBT and V_{rrm}: 1200V, I_{dav}: 40A Diode Bridge in VUI30-12N1 for upto 15KW power
- V_{ds}: 500V, I_d: 130A rated MOSFET in a Diode Bridge rated at V_{rrm}: 500V, I_{dav}: 47A in VUM85-05A for upto 30KW power
- Package with DCB ceramic base plate with Isolation Voltage 3600 V~
- Soldering connections for PCB mounting, Low package inductance for high speed switching, Kelvin source for easy drive
- Three such DCB modules form Vienna Rectifier unit which results in a 3-Phase Power Factor front End.

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PartNumber	Division	PN/kW3~ 400V Tc=80°C	Ckt Diag	Package Style	Status
VUM25-05E	-	10	VUM 25	V1-A-Pack	Active Part
VUI30-12N1	IXYS POWER	15	VUI 30	V1-A-Pack	Active Part
VUM85-05A	-	30	VUM 85	V2-Pack	Active Part

Bitte sprechen Sie uns bei Fragen oder Bedarfen an.